



Bill of Materials
TI DESIGNS

TIDM-TM4CFLASHSRAM

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
Parallel SRAM Memory Card									
1	4	C1, C2, C4, C5	0.1uF	CAP, CERM, 0.1 µF, 6.3 V, +/- 10%, X5R, 0402		C1005X5R0J104K		0402	
2	1	C3	10 uF	CAP, CERM, 10 µF, 6.3 V, +/- 20%, X5R, 0603		C0603C106M9PACTU		0603	
3	1	J1		Header, 100mil, 2x2, Tin, TH		PEC02DAAN			
4	1	P1		Connector 49 Pins Dual Row Thru Hole	Samtec	SAM1212-49-ND			
5	1	R1	10 Kohms	RES, 10 k, 5%, 0.063 W, 0402		CRCW040210K0JNED		0402	
6	2	U1, U2		Octal D Type Latch	Texas Instruments	SN74LV373A_PW_20		PW20	
7	1	U3	16 Mbit	ISSI 16Mbit SRAM	ISSI	IS62WV102416DBLL		TSOP48	
Parallel Flash Memory Card									
1	5	C1, C2, C3, C5, C6	0.1uF	10%, X5R, 0402		C1005X5R0J104K		0402	
2	1	C4	10 uF	20%, X5R, 0603		C0603C106M9PACTU		0603	
3	2	J2, J3		Header, 100mil, 2x2, Tin, TH		PEC02DAAN			
4	1	P1		Row Thru Hole	Samtec	SAM1212-49-ND			
5	7	R1, R2, R3, R4, R5, R6, R7	10 Kohms	RES, 10 k, 5%, 0.063 W, 0402		CRCW040210K0JNED		0402	
6	2	U2, U3		Octal D Type Latch	Texas Instruments	SN74LV373A_PW_20		PW20	
7	1	U4	1Gbit	Macronix 1Gbit Flash	Macronix	MX68GL1G0FHT2		TSOP56	

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	1	C1	1000pF	Capacitor, 1000pF, 2kV, 20%, X7R, 1210	Kemet	C1210C102MGRACTU		1210	
2	26	C3, C4, C5, C10, C11, C12, C13, C16, C17, C18, C19, C21, C22, C23, C24, C25, C26, C27, C28, C29, C30, C40, C41, C42, C43, C46	0.1uF	Capacitor, 0.1uF 16V, 10%,0402 X7R	Taiyo Yuden	EMK105B7104KV-F		0402	
3	1	C31	4700pF	Capacitor, 4700pF, 2kV, 10%,X7R, 1812	AVX	1812GC472KAT1A		1812	
4	2	C32, C33	3300pF	Capacitor, 3300pF, 50V, 10%, X7R, 0603	TDK	C1608X7R1H332K		0603	
5	2	C6, C14	1uF	Capacitor, 1uF , X5R, 10V, Low ESR, 0402	Johanson Dielectrics Inc	100R07X105KV4T		0402	
6	3	C7, C15, C20	2.2uF	Capacitor, 2.2uF, 16V, 10%, 0603, X5R	Murata	GRM188R61C225KE15D		0603	
7	6	C8, C9, C44, C45, C47, C48	12pF	Capacitor, 12pF, 50V, 5%, 0402, COG	Murata	GRM1555C1H120JZ01D		0402	
8	5	D0, D1, D2, D3, D4		Green LED 0603	Everlight	19-217/G7C-AL1M2B/3T		0603	
9	7	J1, J2, J3, J4, J5, J6, J7		Jumper, 0.100, Gold, Black, Open	3M	969102-0000-DA			
10	1	JP1		Header, 2x3, 0.100, T-Hole, Vertical Unshrouded, 0.230 Mate, gold	FCI	67996-206HLF			
11	2	JP2, JP3		Header, 1x2, 0.100, T-Hole, Vertical Unshrouded, 0.220 Mate	FCI	68001-102HLF			
12	2	JP4, JP5		Header, 2x2, 0.100, T-Hole, Vertical Unshrouded, 0.230 Mate	FCI	67997-104HLF			
13	8	R1, R2, R3, R4, R5, R29, R35, R44	10 KOhm	Resistor, 10k ohm, 1/10W, 5%, 0402 Thick Film	Yageo	RC0402FR-0710KL		0402	
14	3	R17, R26, R36	100 KOhm	100k 5% 0402 resistor smd	Rohm	MCR01MRTJ104		0402	
15	2	R18, R51	100 Ohm	Resistor 0402 100 ohm 5%	Rohm	MCR1MRTJ101		0402	
16	4	R23, R21, R22, R24	49.9 Ohm	Resistor 49.9 ohm 0402. 1 %	Rohm	MCR01MRTF49R9		0402	
17	1	R25	4.87 Kohm	Resistor 4.87k 1% 0402 smd	Rohm	MCR01MRTF4871		0402	
18	1	R28	5.6 Kohm	Resistor, 5.6k ohm, 1/10W, 5%, 0402	Panasonic	ERJ-2GEJ562X		0402	
19	4	R32, R43, R45, R46	75 Ohm	resistor 75 ohm 0402 5%	Rohm	MCR01MRTJ750		0402	
20	2	R34, R52	1 MOhm	Resistor, 1M OH, 1/10W, 5% 0603 SMD	Panasonic	ERJ-3GEYJ105V		0603	
21	1	R38	51 Ohm	Resistor, 51 ohm, 1/10W, 5%, 0402	Panasonic	ERJ-2GEJ510X		0402	
22	1	R42	1 MOhm	Resistor, 1M ohm, 1/10W, 5%, 0402	Rohm	MCR01MRTF1004		0402	
23	1	R47	1 MOhm	RES 1M OHM 5% 1206 TF	Panasonic	ERJ-8GEYJ105V		1206	
24	2	R49, R50	2 Kohm	Resistor, 2.0k ohm, 1/10W, 5%, 0402	Panasonic	ERJ-3GEYJ202V		0402	

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
25	12	R6, R7, R8, R10, R11, R15, R16, R19, R20, R39, R40, R41	0 Ohm	Resistor, 0 ohm, 1/10W, 5%, 0402	Panasonic	ERJ-2GE0R00X		0402	
26	5	R9, R27, R30, R31, R33	330 Ohm	Resistor, 330 ohm, 1/10W, 5%, 0402	Yageo	RC0402FR-07330RL		0402	
27	4	RESET, USR_SW1, USR_SW2, WAKE		Switch, Tact 6mm SMT, 160gf	Omron	B3S-1000			
28	1	U1		Tiva, MCU TM4C1294NCPDT 128 QFP with Ethernet MAC + PHY	Texas Instruments	TM4C1294NCPDT			TQFP-128
29	1	U10		Transformer, ethernet, 1 to 1. SOIC 16	Pulse Electronics	HX1198FNL			SOIC-16
30	1	U13		Diode, 8 chan, +/-15KV, ESD Protection Array, SO-8	Semtech	SLVU2.8-4.TBT			SO-8
31	1	U14		Connector, RJ45 NO MAG, shielded THRU HOLE	TE Connectivity	1-406541-5			
32	2	U2, U3		IC 4CH ESD SOLUTION, W/CLAMP 6SON	Texas Instruments	TPD4S012DRYR			
33	1	U20		TIVA MCU TM4C123GH6PMI	Texas Instruments	TM4C123GH6PMI			QFP-64
34	1	U22		USB Micro B receptacle right angle with guides	FCI	10118194-0001LF			
35	1	U4		Fault protected power switch, dual channel, 8-SON	Texas Instruments	TPS2052BDRBR			
36	1	U5		3.3V LDO TI TPS73733DRV fixed out 5V in	Texas Instruments	TPS73733DRV			
37	1	U6		Header 2x5, 0.050, SM, Vertical Shrouded	Samtec	SHF-105-01-S-D-SM			
38	1	U7		USB Micro AB receptacle. Right angle with through guides	Hirose	ZX62D-AB-5P8			
39	4	X6, X7, X8, X9		Header, 2x10, T-Hole Vertical unshrouded stacking	Samtec	SSW-110-23-S-D			
40	1	Y1	25 MHz	Crystal 25 MHz 3.2 x 2.5 mm	NDK	NX3225GA-25.000M-STD-CRG-2			
41	1	Y2	16 MHz	Crystal 16 MHz 3.2 x 2.5 mm 4 pin	NDK	NX3225GA-16.000M-STD-CRG-2			
42	1	Y3	32768 Hz	Crystal, 32.768 KHz Radial Can	Citizen Finetech Miyota	CMR200T-32.768KDZY-UT			
PCB Do Not Populate List (Shown for Information only)									
43	1	C2	0.1uF	Capacitor, 0.1uF 16V, 10%, 0402 X7R	Taiyo Yuden	EMK105B7104KV-F		0402	
44	3	H1, H4, H6		Screw, #4 x 0.625" Pan Head, Sheet Metal, Phillips/Slotted (for fan)	McMaster	90077A112			
45	3	R12, R12, R14	5.6 KOhm	Resistor, 5.6k ohm, 1/10W, 5%, 0402	Panasonic	ERJ-2GEJ562X		0402	
46	1	R48	52.3 KOhm	Resistor 0402 1% 52.3k	Rohm	TRR01M2PF5232		0402	
47	17	TP1, TP2, TP3, TP4, TP5, TP6, TP7, TP8, TP9, TP10, TP11, TP12, TP13, TP14, TP15, TP16, TP17		Terminal, Test Point Miniature Loop, Red, T-Hole	Keystone	5000			
48	1	X1		Header, 2x7, 0.100, T-Hole, Vertical, Unshrouded, 0.230 Mate	FCI	67997-114HLF			
49	1	X11A		Valvano style bread board connect. Right Angle extended, 1 x 49 0.100 pitch.	Samtec	TSW-149-09-F-S-RE			
50	1	X11B		valvano style breadboard header.	Samtec	TSW-149-08-F-S-RA			

IMPORTANT NOTICE FOR TI REFERENCE DESIGNS

Texas Instruments Incorporated ("TI") reference designs are solely intended to assist designers ("Buyers") who are developing systems that incorporate TI semiconductor products (also referred to herein as "components"). Buyer understands and agrees that Buyer remains responsible for using its independent analysis, evaluation and judgment in designing Buyer's systems and products.

TI reference designs have been created using standard laboratory conditions and engineering practices. **TI has not conducted any testing other than that specifically described in the published documentation for a particular reference design.** TI may make corrections, enhancements, improvements and other changes to its reference designs.

Buyers are authorized to use TI reference designs with the TI component(s) identified in each particular reference design and to modify the reference design in the development of their end products. HOWEVER, NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY THIRD PARTY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT, IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI REFERENCE DESIGNS ARE PROVIDED "AS IS". TI MAKES NO WARRANTIES OR REPRESENTATIONS WITH REGARD TO THE REFERENCE DESIGNS OR USE OF THE REFERENCE DESIGNS, EXPRESS, IMPLIED OR STATUTORY, INCLUDING ACCURACY OR COMPLETENESS. TI DISCLAIMS ANY WARRANTY OF TITLE AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, QUIET ENJOYMENT, QUIET POSSESSION, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS WITH REGARD TO TI REFERENCE DESIGNS OR USE THEREOF. TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY BUYERS AGAINST ANY THIRD PARTY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON A COMBINATION OF COMPONENTS PROVIDED IN A TI REFERENCE DESIGN. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, SPECIAL, INCIDENTAL, CONSEQUENTIAL OR INDIRECT DAMAGES, HOWEVER CAUSED, ON ANY THEORY OF LIABILITY AND WHETHER OR NOT TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES, ARISING IN ANY WAY OUT OF TI REFERENCE DESIGNS OR BUYER'S USE OF TI REFERENCE DESIGNS.

TI reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques for TI components are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

Reproduction of significant portions of TI information in TI data books, data sheets or reference designs is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards that anticipate dangerous failures, monitor failures and their consequences, lessen the likelihood of dangerous failures and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in Buyer's safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed an agreement specifically governing such use.

Only those TI components that TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components that have **not** been so designated is solely at Buyer's risk, and Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.